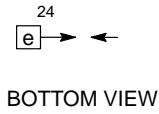
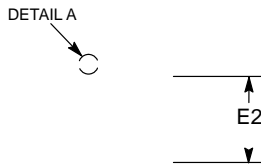
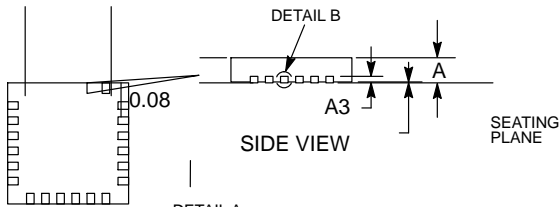
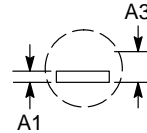
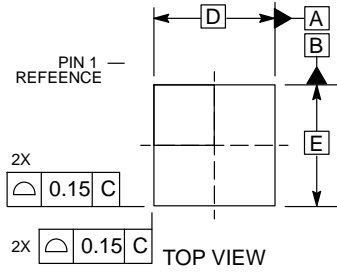


QFN24, 4x4, 0.5P  
CASE 485L  
ISSUE B

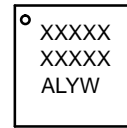
DATE 05 JUN 2012

f 2.046.041 cm 0 0  
SCALE 2:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

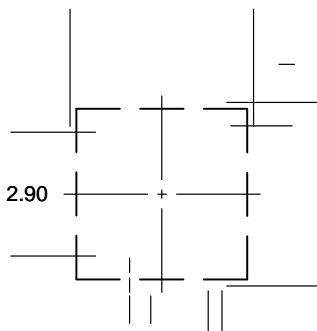
GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb iFree Package

(Note: Microdot may be in either location)

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS